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wherein the electronic circuit module is contained in the hollow portion of the hollow resin case, and

the first slit spatially connects the hollow portion and an outside of the hollow resin case.

2. (Amended) The contactless data carrier according to claim 1, further comprising a shielding plate, wherein the shielding plate is provided in the hollow portion of the hollow resin case and between the electronic circuit module and the first slit to partition the hollow portion and is provided with a second slit, the hollow portion being on a side of the electronic circuit module with respect to the shielding plate and communicating with the outside of the hollow resin case through the second slit and the first slit.

6. (Amended) The contactless data carrier according to claim 1, wherein a plurality of shielding plates are provided in the hollow portion of the hollow resin case and between the electronic circuit module and the first slit to partition the hollow portion, and each of the plurality of shielding plates is provided with a slit.